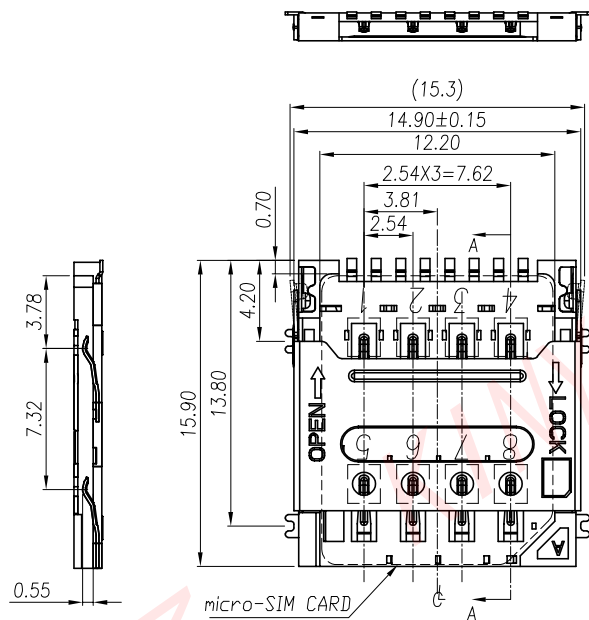


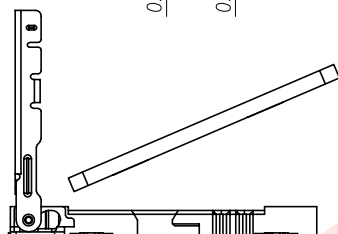
*所有原料材质, 生产制程, 电镀必须符合ROHS要求

NOTES:

1. ELECTRICAL CHARACTERISTICS
 - 1-1. CONTACT RESISTANCE: 60 Milliohms Max
 - 1-2. INSULATION RESISTANCE: 1,000 Megohms Min.
 - 1-3. DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE.
2. MECHANICAL CHARACTERISTICS
 - 2-1. OPERATION TEMPERATURE RANGE: -25°C~+70°C
 - 2-2. DURABILITY: 5000 CYCLES
3. MATERIAL:
 - 3-1. HOUSING: THERMOPLASTIC, UL 94-V0
 - 3-2. TERMINAL: PHOSPHOR BRONZE, T=0.15
 - 3-3. SHELL: STAINLESS STEEL, T=0.15
4. FINISHED:
 - 4-1. TERMINAL: Ni PLATED UNDER, Au PLATED ON CONTACT AREA, G/F PLATED ON SOLDER TAIL



SECTION: A-A

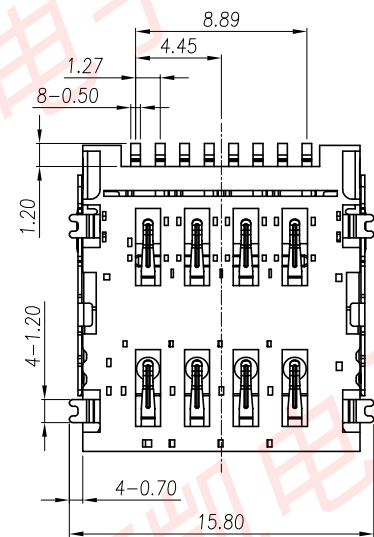


STEP 1 INSERT Micro-SIM CARD

STEP 2 PUSH THE SHELL

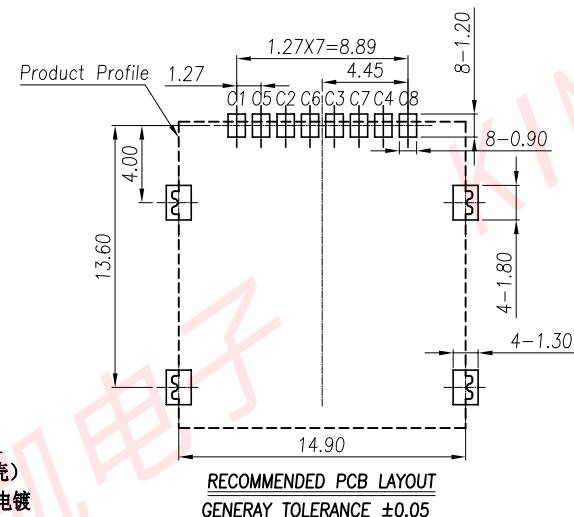
STEP 3 FINISH

SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	RESERVED
C5	GND
C6	VPP
C7	I/O
C8	RESERVED



+0.05 (U.S.L.)
(HOUSING BOTTOM)
-0.15 (L.S.L.)
SMT SIDE
COPLANARITY
0.10 MAX

SM150-T6150-11-W
系列码
SM150:MICRO SIM H1.5
脚型码
T:SMT
电镀码 (端子)
61:端子Au 30u"/(G/F)
流水码
电镀码 (外壳)
50:素材, 无电镀



KINY

东莞市摩凯电子有限公司

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE
DIMENSION TOLERANCE
X.X: ± 0.20
X.XX: ± 0.10
X.XXX: ± 0.05
ANGULAR: ± 2'

PRODUCT NAME : MICRO SIM H1.5 掀盖	DRAWING: Janyz	DATE: 2018.11.22
PRODUCT NO. : SM150-T6150-11-W	CHECK: Alex	DATE: 2018.11.22
DRAWING NO. : D-SM150-T6150-11-W	APPROVED: Alex	DATE: 2018.11.22
SCALE: 1:1	DWG ID: C D	REV.: A
		PAGE: 1 OF 1

A	---	NEW RELEASE	janyz	2018.11.22
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE

1

2

3

4

5

6